

注記 NOTES

1. 使用材料 MATERIAL

ハウジング : ポリアミド46、ガラス充填、UL94V-0 (白)
 HOUSING : POLYAMIDE46, GLASS FILLED, UL94V-0(WHITE)
 アクチュエータ : ポリフェニレンサルファイド、ガラス充填、UL94V-0 (黒)
 ACTUATOR : POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0(BLACK)
 ターミナル : リン青銅 (t=0.2)
 TERMINAL : PHOSPOR BRONZE
 メッキ
 コントクト部: 金メッキ 0.1マイクロメートル以上
 テール部: 金メッキ 0.05マイクロメートル以上
 下地: ニッケル 1.0マイクロメートル以上

PLATED
 CONTACT AREA : GOLD 0.1 MICROMETER MINIMUM
 TAIL AREA : GOLD 0.05 MICROMETER MINIMUM
 UNDER PLATING : NICKEL 1.0 MICROMETER MINIMUM
 金具 : リン青銅、ニッケル下地純銅メッキ (t=0.2)
 FITTING NAIL : PHOSPOR BRONZE, TIN OVER NICKEL PLATING

2. エンボステープ梱包時は、アクチュエータがロックした状態とする。
 IN THE PACKAGE, ACTUATOR OF PART NO. 52745-***59 SHOULD BE LOCKED.
 △ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 H に対し上方向 0.1 MAX.、下方向 0.15 MAX. とする。
 MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM H
 UPPER DIRECTION: 0.1 MAX., LOWER DIRECTION: 0.15 MAX.

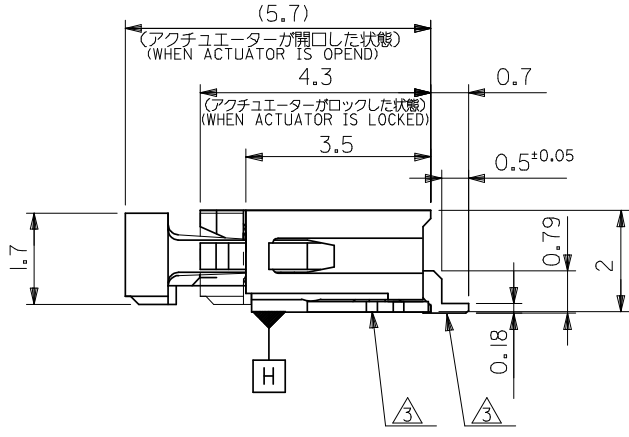
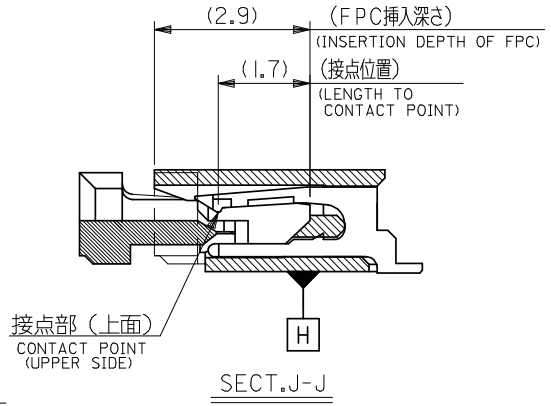
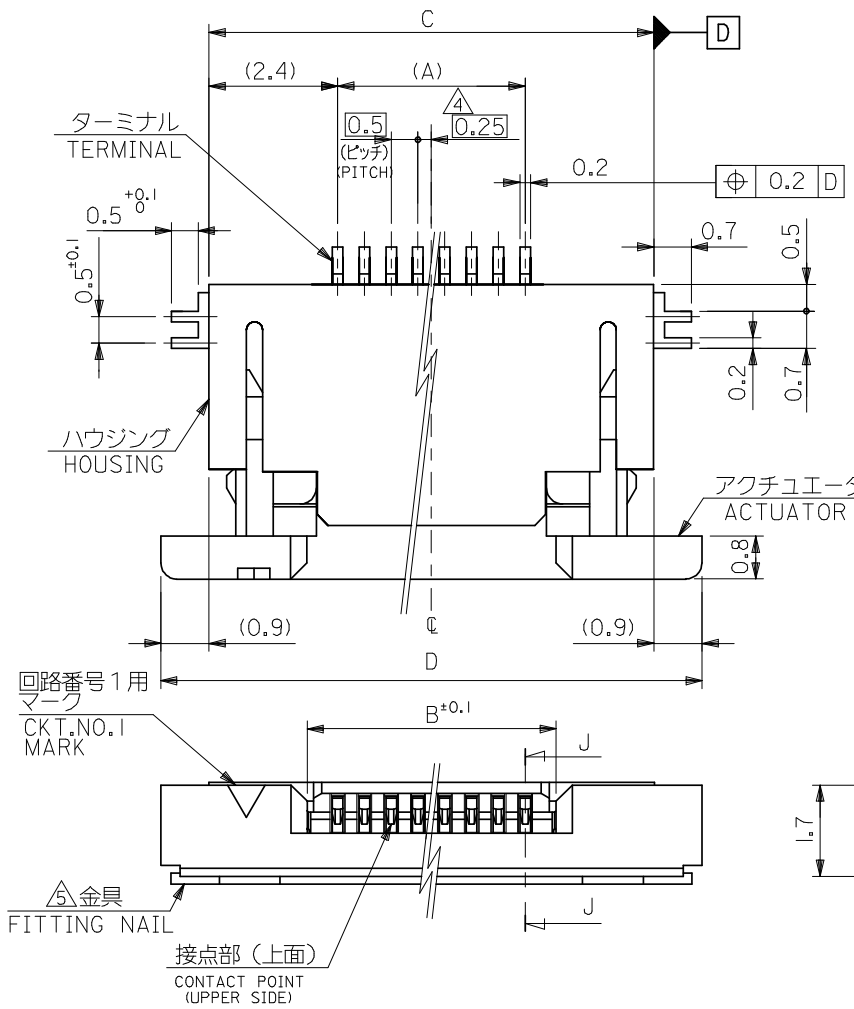
△偶数極に適用。
 APPLY FOR EVEN CIRCUIT.

△パターンはくり止め用金具
 FITTING NAIL FOR PREVENTION OF PEELING
 OF P.C.B. PATTERN.

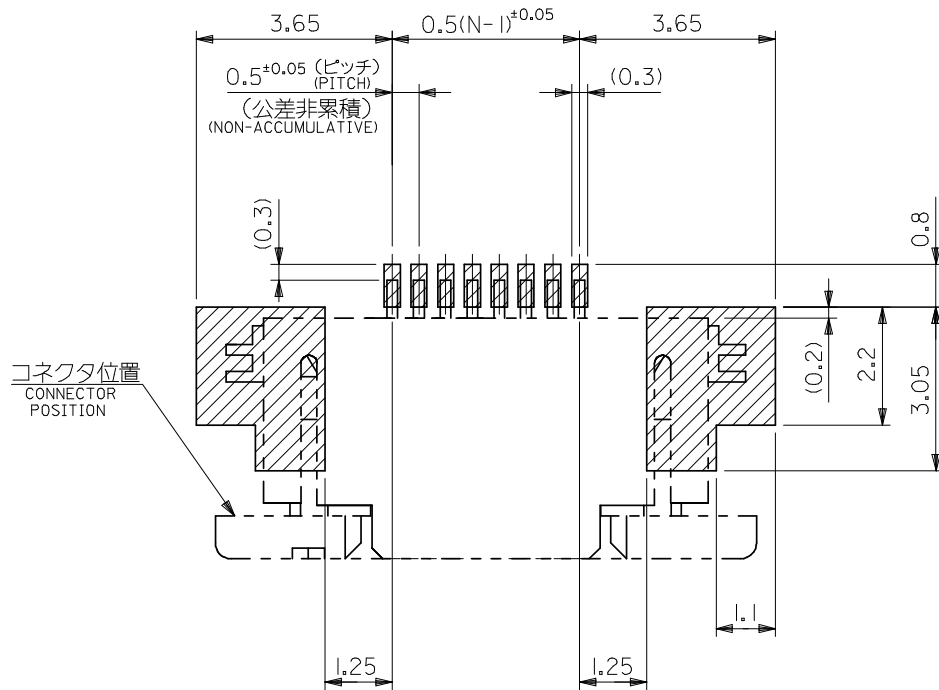
6. 本製品は 54745-***17 の部分金メッキ品である。
 THIS PRODUCT IS SELECTIVE GOLD PLATING OF 52745-***17.

16.1	14.3	10.65	9.5	52745-2097	52745-2059	20
15.6	13.8	10.15	9.0	-1997	-1959	19
15.1	13.3	9.65	8.5	-1897	-1859	18
14.6	12.8	9.15	8.0	-1797	-1759	17
14.1	12.3	8.65	7.5	-1697	-1659	16
13.6	11.8	8.15	7.0	-1597	-1559	15
13.1	11.3	7.65	6.5	-1497	-1459	14
12.6	10.8	7.15	6.0	-1397	-1359	13
12.1	10.3	6.65	5.5	-1297	-1259	12
11.6	9.8	6.15	5.0	-1197	-1159	11
11.1	9.3	5.65	4.5	-1097	-1059	10
10.6	8.8	5.15	4.0	-0997	-0959	9
10.1	8.3	4.65	3.5	-0897	-0859	8
9.6	7.8	4.15	3.0	-0797	-0759	7
9.1	7.3	3.65	2.5	-0697	-0659	6
8.1	6.3	2.65	1.5	52745-0497	52745-0459	4
D	C	B	(A)	EMBOSSSED TAPE	MATERIAL NO.	極数
				ORDER No. オーダー番		CIRCUIT

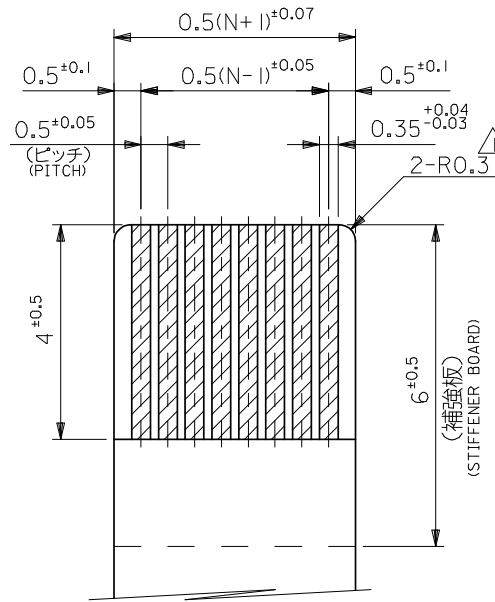
52745-***59 MODEL NO.



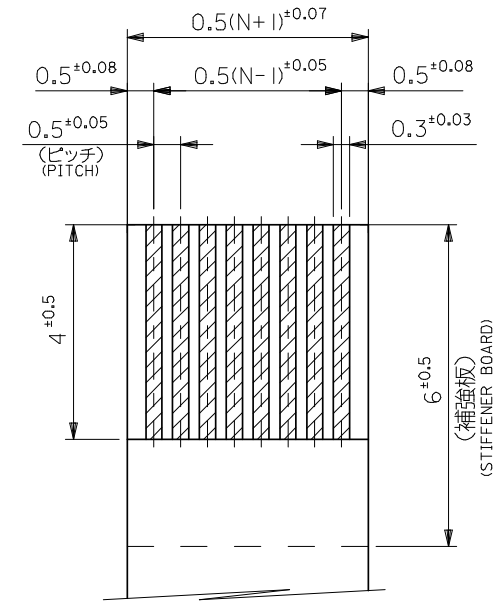
REVISED EC NO: J2008-4308 DRWN: NABEI 2008/06/27 CH'KD: THARUYAMA 2008/06/30 APPR: NUKITA 2008/06/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY M. NABEI	DATE '05/02/14	TITLE 0.5 FPC CONN ASSY ZIF UPR CONT -LEAD FREE-			
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE '05/02/14				
	30 OVER	±0.3	APPROVED BY N. UKITA	DATE '05/02/14	MOLEX INCORPORATED			
	ANGULAR	±3 °	MATERIAL NO.	DOCUMENT NO.				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE TABLE		SD-52745-050		1 OF 2	



参考基板レイアウト
P.C.BOARD PATTERN
DIMENSION (REF.)
(マウント面)
(MOUNTING SIDE)



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)



適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)

FPCについて:
打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION: FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL: STIFFENER FILM: POLYIMIDE
BONDING AGENT: THERMOSETTING BONDING AGENT

注記 NOTES

△ R0.3は、FPCの導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

52745-***59 MODEL NO.

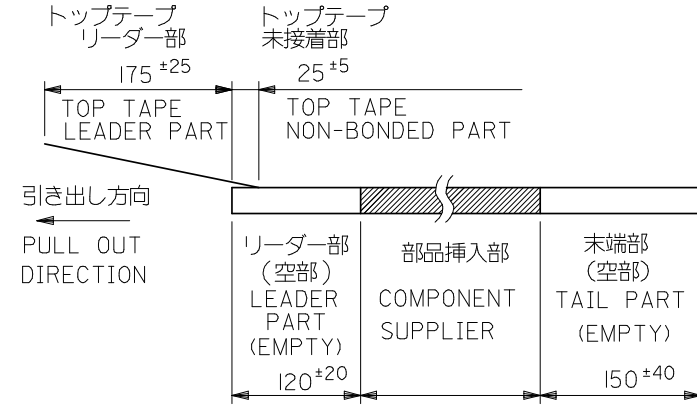
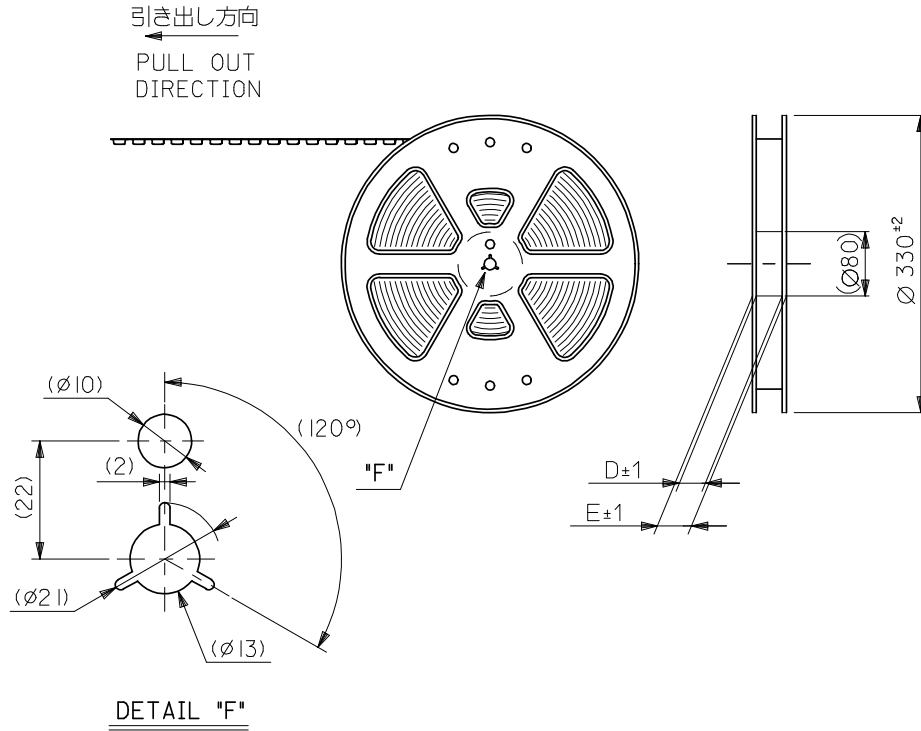
REVISED EC NO: J2008-4308 DRWN: NABEI 2008/06/27 CHKD: THARUYAMA 2008/06/30 APPR: NUKITA 2008/06/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M. NABEI	DATE '05/02/14	TITLE 0.5 FPC CONN ASSY ZIF UPR CONT -LEAD FREE-	
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE '05/02/14	APPROVED BY N. UKITA	
	30 OVER	±0.3	DATE '05/02/14	MATERIAL NO. SEE SHEET 1		DOCUMENT NO. SD-52745-050
	ANGULAR	±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SHEET NO. 2 OF 2	
REV	DESCRIPTION		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

注記 NOTES

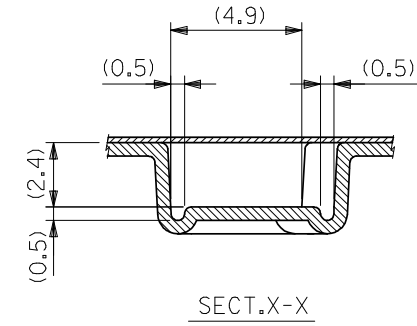
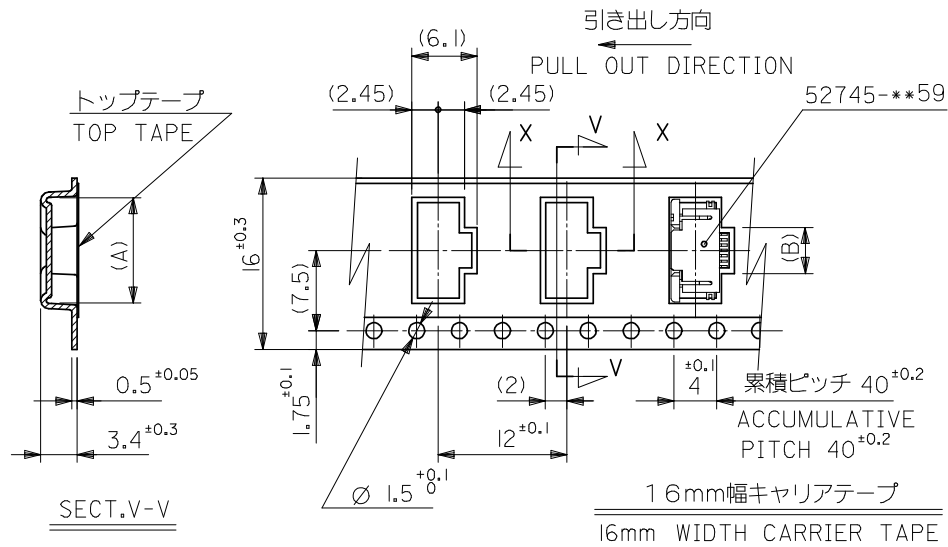
- 製品番号 52745-**-59 の梱包状態はアクチュエータがロックした状態とする。
製品詳細寸法は製品単体図面を参照して下さい。
IN THE PACKAGE, ACTUATOR OF PART NO. 52745-**-59 SHOULD BE LOCKED FOR DETAIL OF CONNECTOR DIMENSIONS, PLEASE SEE THE DRAWING OF CONNECTOR ITSELF (NOT PACKAGED).
- 梱包数量：1000個/リール
NUMBER OF CONNECTORS: 1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH

トップテープ リーダー部	トップテープ 未接着部
175 ±25	25 ±5
TOP TAPE LEADER PART	TOP TAPE NON-BONDED PART
- 材料

キャリアテープ	ポリプロピレン (PP)
トップテープ	PET, PE, PEF
リール	ポリスチレン (PS) <リサイクル材を含む>
MATERIAL CARRIER TAPE	POLYPROPYLENE
TOP TAPE	PET, PE, PEF
REEL	POLYSTYRENE (PS)
	<RECYCLE MATERIAL CONTAINED>
- ELV AND RoHS COMPLIANT.
- 本製品は52745-**-97の梱包違い品、シリカゲル入りハイバリア仕様である。
THIS PRODUCT IS HIGH BARRIER PACKAGE INCLUDING SILICAGEL FOR 52745-**-97.
- 開梱後の保管条件に注意のこと。(PS-52745-051参照)
REFER TO PS-52745-051 FOR CONDITIONS AFTER OPEN.



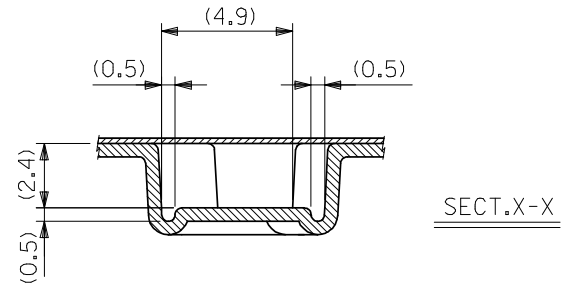
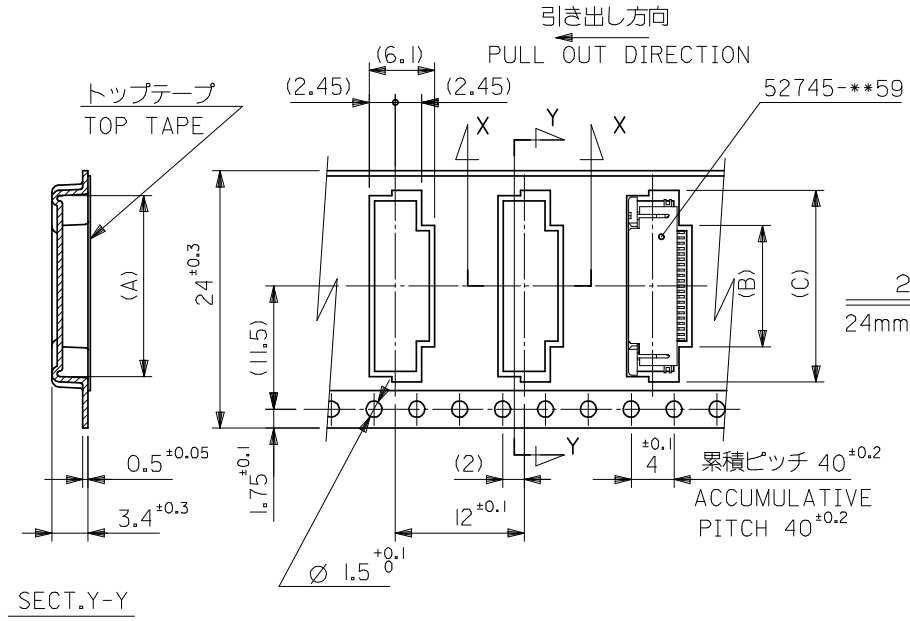
REVISED EC NO: J2008-4177 DRWN: ASUZUKI 2008/06/12 CHKD: MATSUMOTO 2008/06/12 APPR: NUKITA 2008/06/13	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	52745-**-83	MODEL NO.
		10 UNDER ±---		DRAWN BY DATE M. NABEI '08/05/29		TITLE EMBOSSSED TAPE PKG. FOR 52745-**-59 HIGH BARRIER PKG.	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		10 OVER 30 UNDER ±---		CHECKED BY DATE H. MATSUMOTO '08/05/29			MOLEX INCORPORATED	SHEET NO. 1 OF 3
		30 OVER ±---		APPROVED BY DATE N. UKITA '08/05/29				
		ANGULAR ±--- °		MATERIAL NO.		DOCUMENT NO.		SD-52745-052
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



16	21.4	17.4	2.8	8.4	52745-0483	4
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(B)	(A)	MATERIAL NO.	極数 CIRCUIT

52745-**-83 MODEL NO.

REVISED EC NO: J2008-4177 DRWN: ASUZUKI01 2008/06/12 CHKD: MATSUMOTO 2008/06/12 APPR: NUKITA 2008/06/13	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	REV	10 UNDER ± ---	DRAWN BY DATE M. NABEI '08/05/29	TITLE EMBOSSD TAPE PKG. FOR 52745-**-59 HIGH BARRIER PKG.		
		10 OVER 30 UNDER ± ---	CHECKED BY DATE H. MATSUMOTO '08/05/29	MOLEX INCORPORATED		
		30 OVER ± ---	APPROVED BY DATE N. UKITA '08/05/29	MATERIAL NO.	DOCUMENT NO.	SHEET NO.
		ANGULAR ± --- °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	SD-52745-052	2 OF 3



24	29.4	25.4	17.4	10.8	16.4	52745-2083	20
			16.4	9.8	15.4	-1883	18
			15.9	9.3	14.9	-1783	17
			15.4	8.8	14.4	-1683	16
			14.9	8.3	13.9	-1583	15
			14.4	7.8	13.4	-1483	14
			13.9	7.3	12.9	-1383	13
			13.4	6.8	12.4	-1283	12
			12.9	6.3	11.9	-1183	11
			12.4	5.8	11.4	-1083	10
			11.4	4.8	10.4	-0883	8
			10.9	4.3	9.9	-0783	7
10.4	3.8	9.4	52745-0683	6			
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	MATERIAL NO.	極数 CIRCUIT

REVISED EC NO: J2008-4177 DRWN: ASUZUKI01 2008/06/12 CHKD: MATSUMOTO 2008/06/12 APPR: NUKITA 2008/06/13	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
				MM ONLY	---	METRIC	☉ □	
		10 UNDER	± ---	DRAWN BY	DATE	TITLE		
		10 OVER 30 UNDER	± ---	M. NABEI	'08/05/29	EMBOSSSED TAPE PKG. FOR 52745-***59 HIGH BARRIER PKG.		
		30 OVER	± ---	CHECKED BY	DATE			
		APPROVED BY	DATE	MOLEX MOLEX INCORPORATED				
		N. UKITA	'08/05/29	DOCUMENT NO.				
		ANGULAR	± --- °	SEE TABLE		SD-52745-052		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		SHEET NO. 3 OF 3		